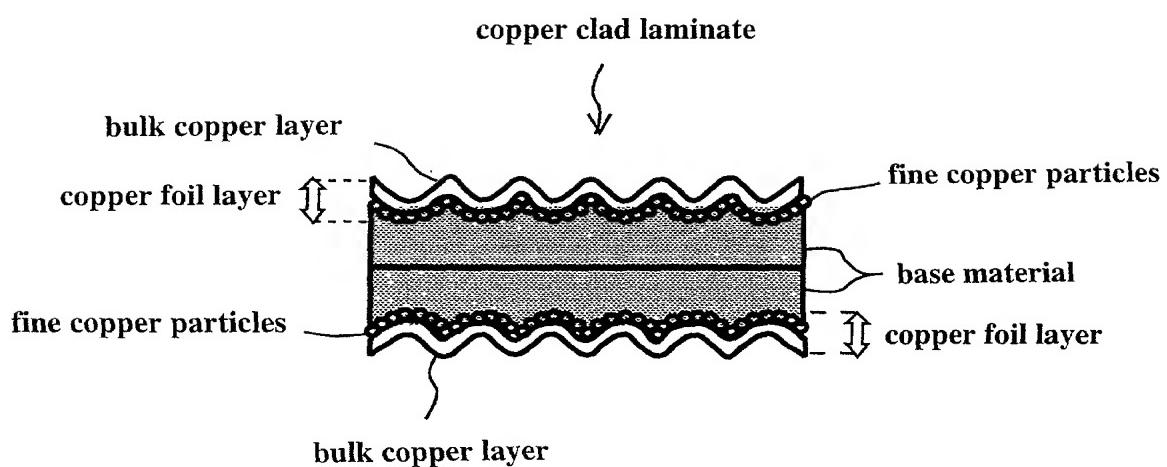
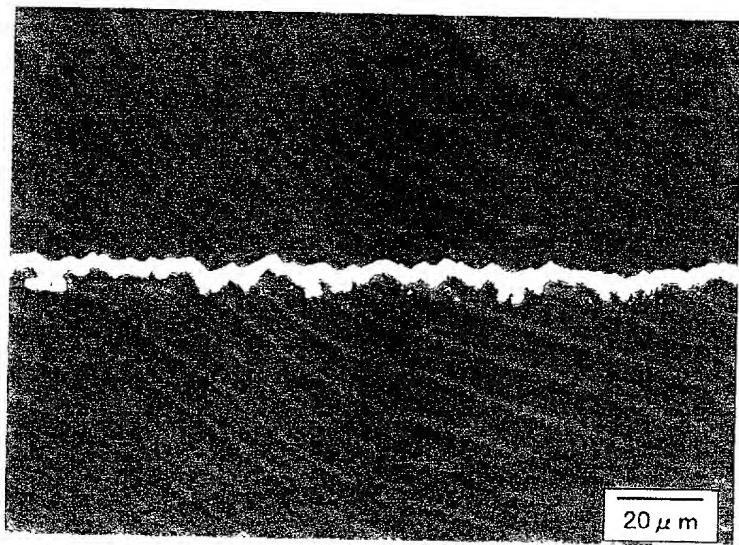


FIG. 1



09855282 051694

FIG. 2



09355332 05150..

surface roughness (R_z) / μm

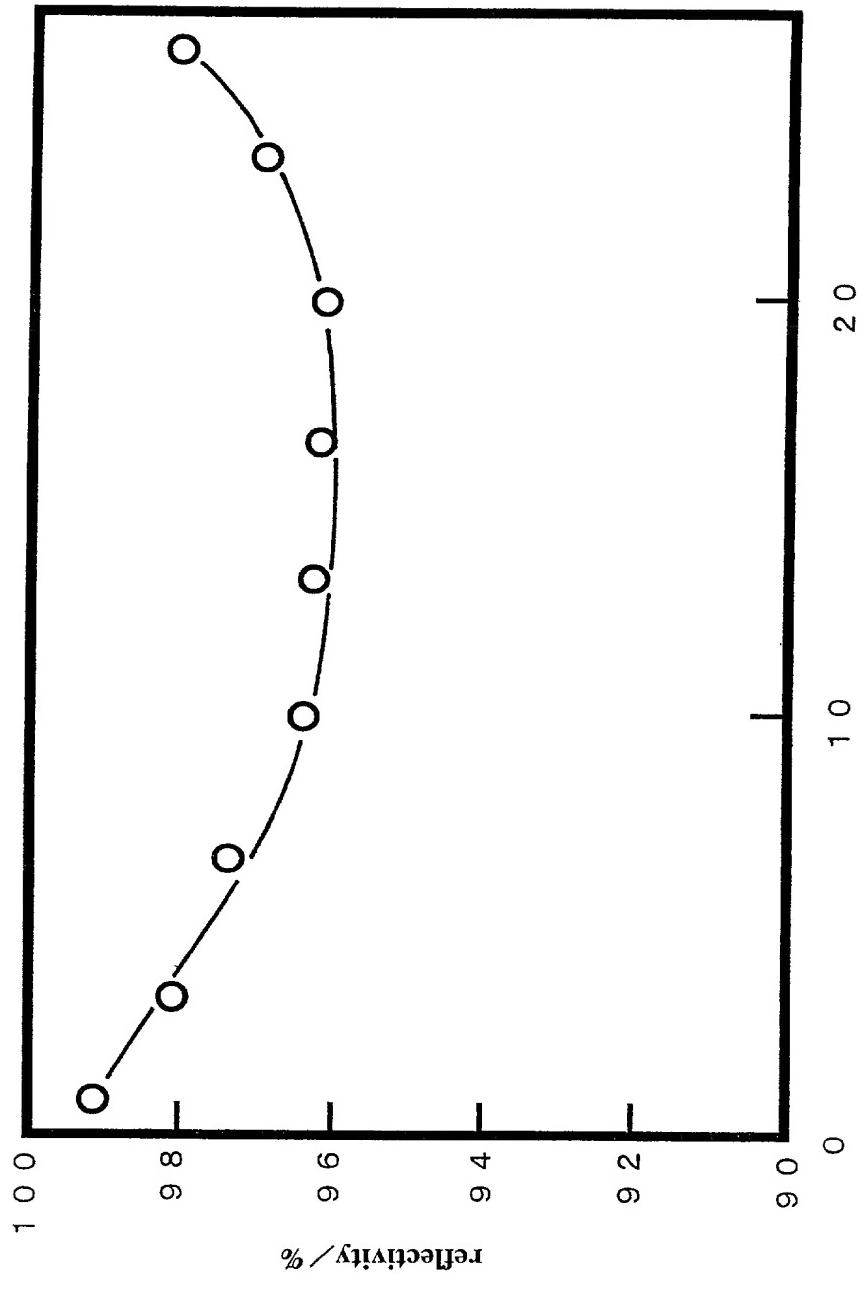
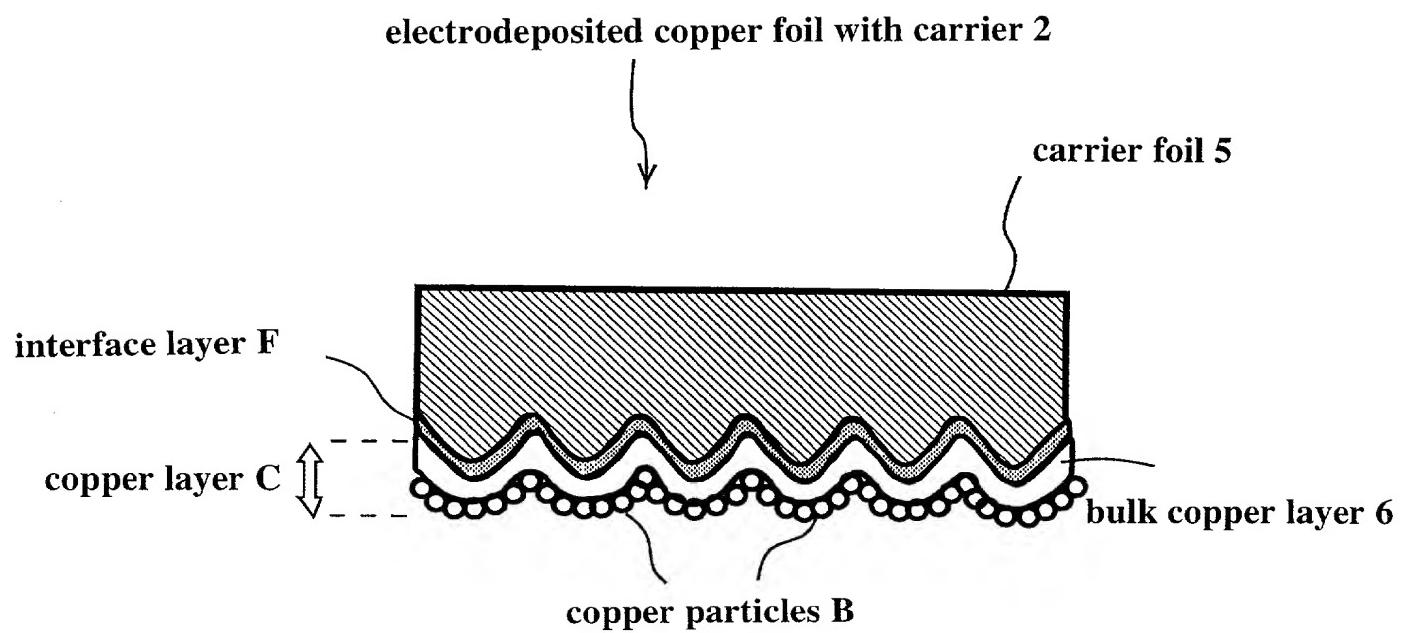


FIG. 3

FIG. 4



0 9 8 5 5 3 8 2 0 5 3 1 5 0 3

FIG. 5

(a) Manufacturing of copper clad laminate

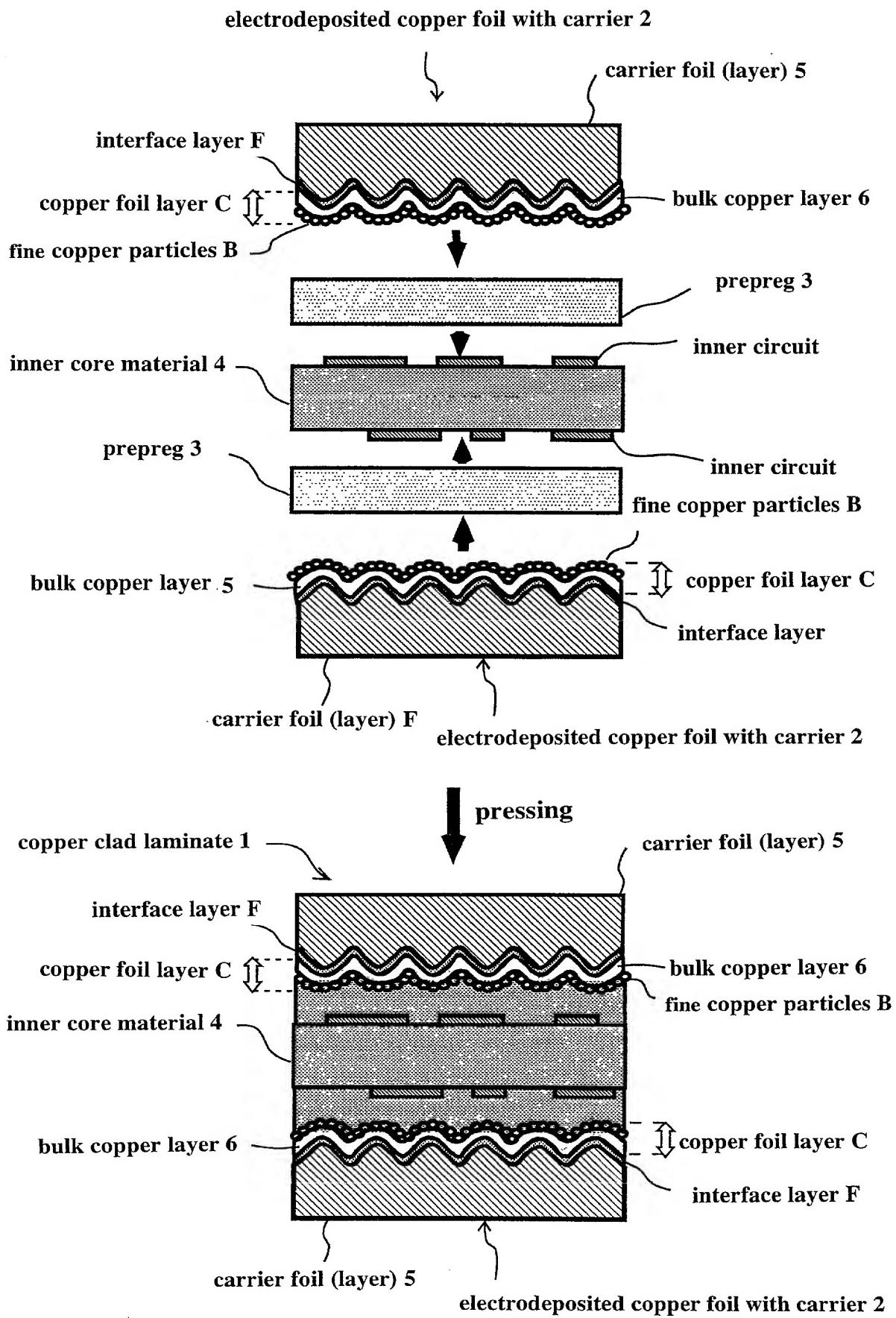
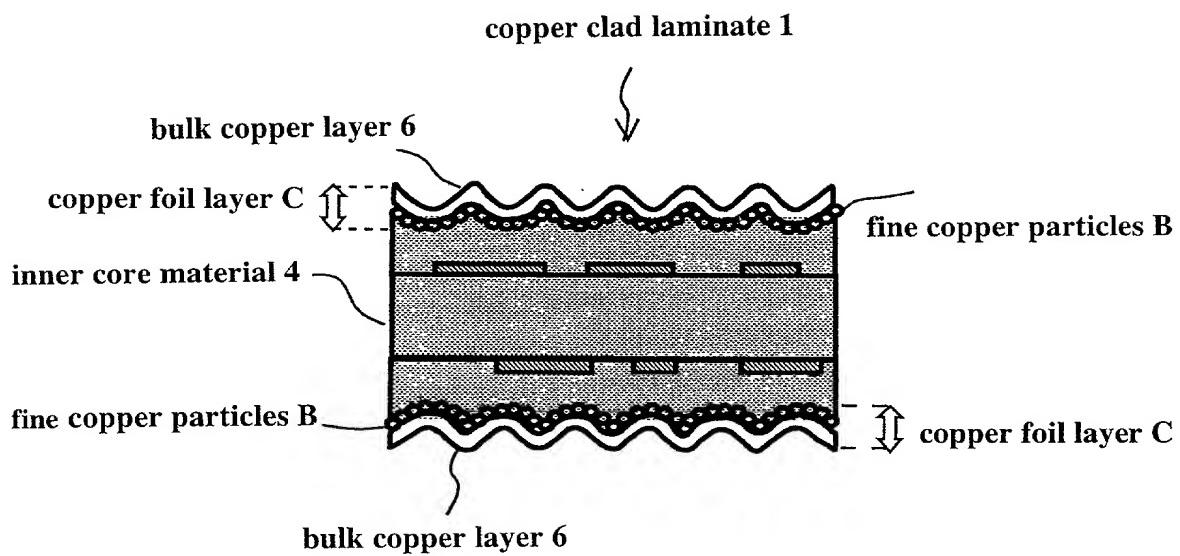


FIG. 6

(b) Peeling of Carrier Foil



(c) Laser Treatment for Forming Holes

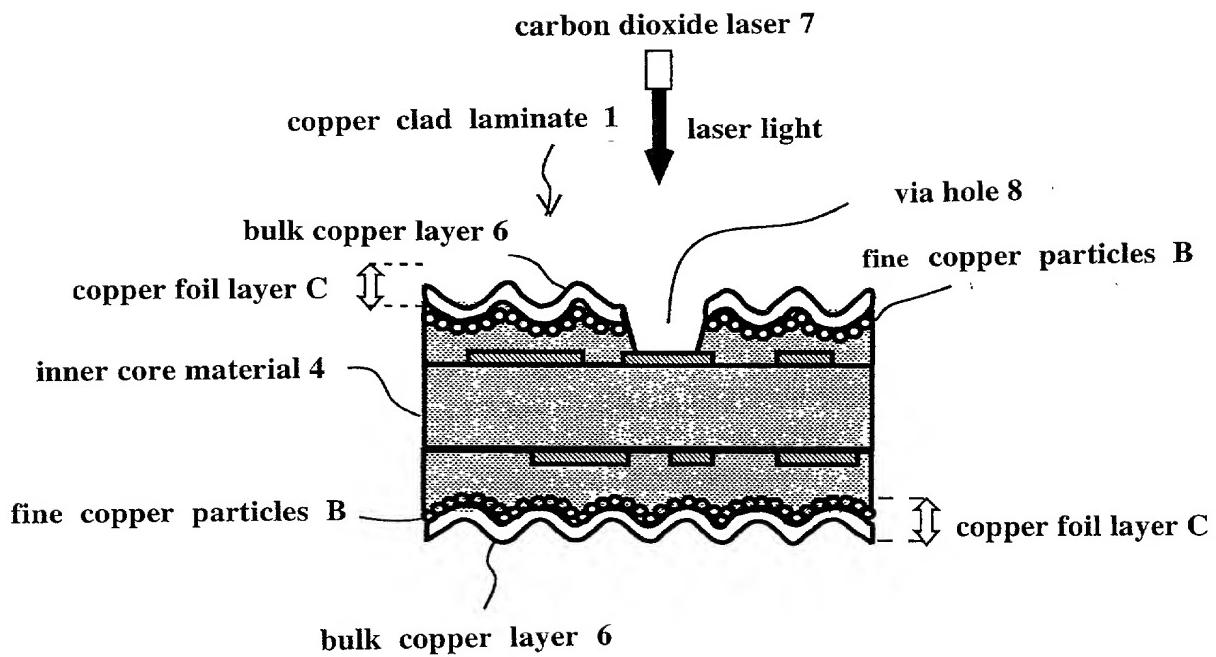
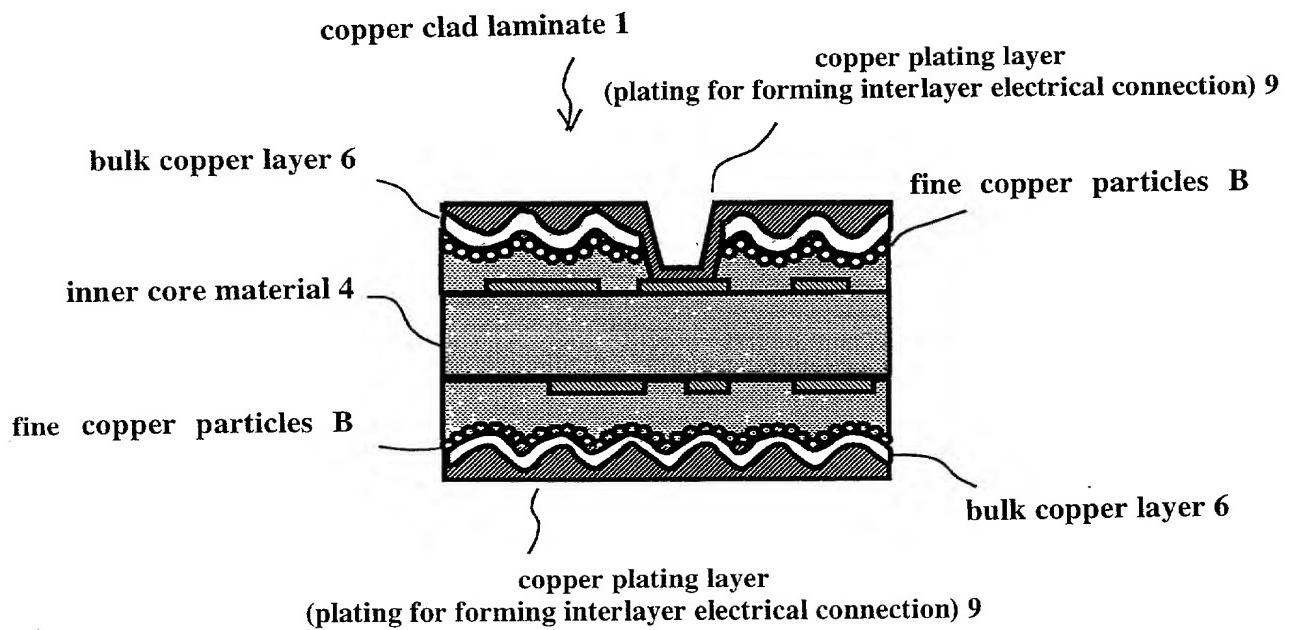


FIG. 7

(d) Copper Plating for Forming Interlayer Electrical Connection



(e) Forming Etching Resist Layers

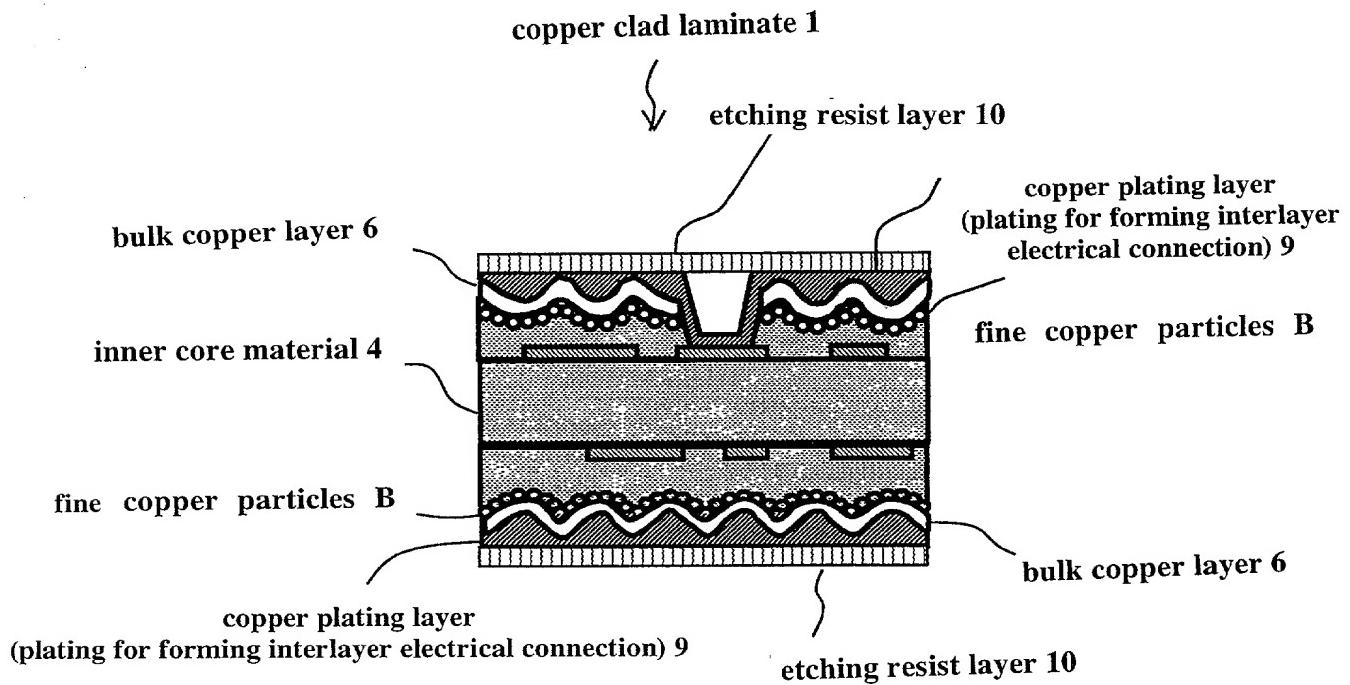
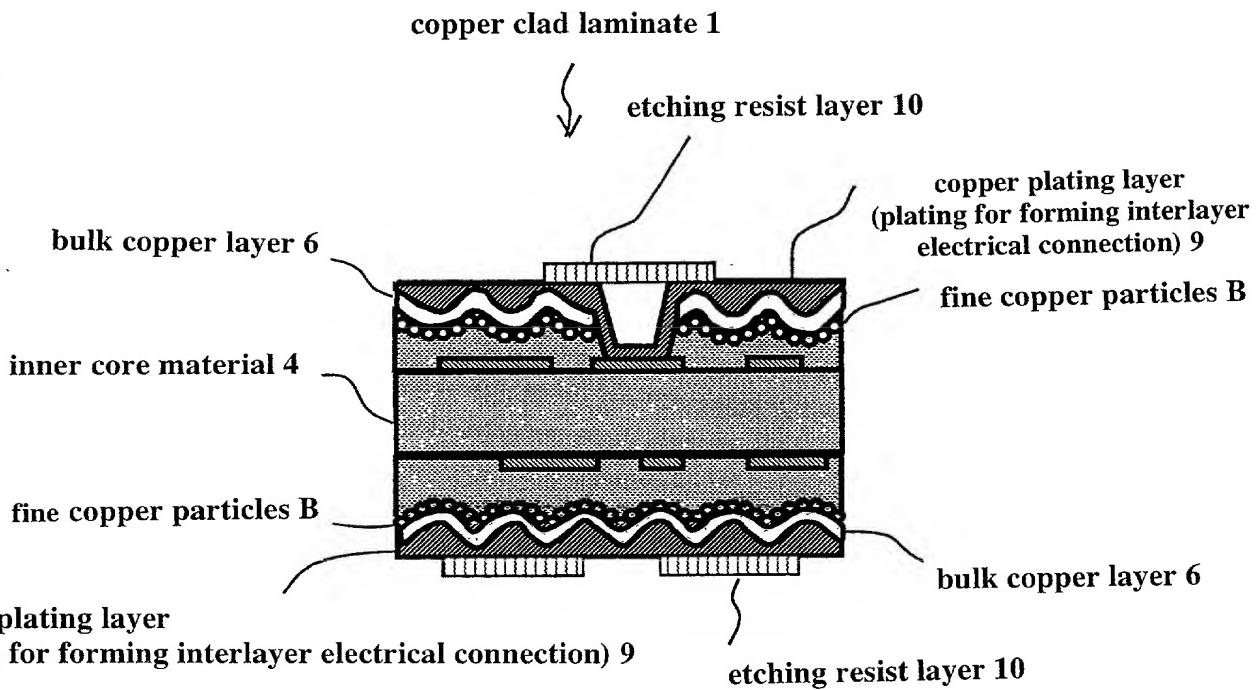


FIG. 8

(f) Exposing and Developing the Etching Resist Layers



(g) Copper Etching

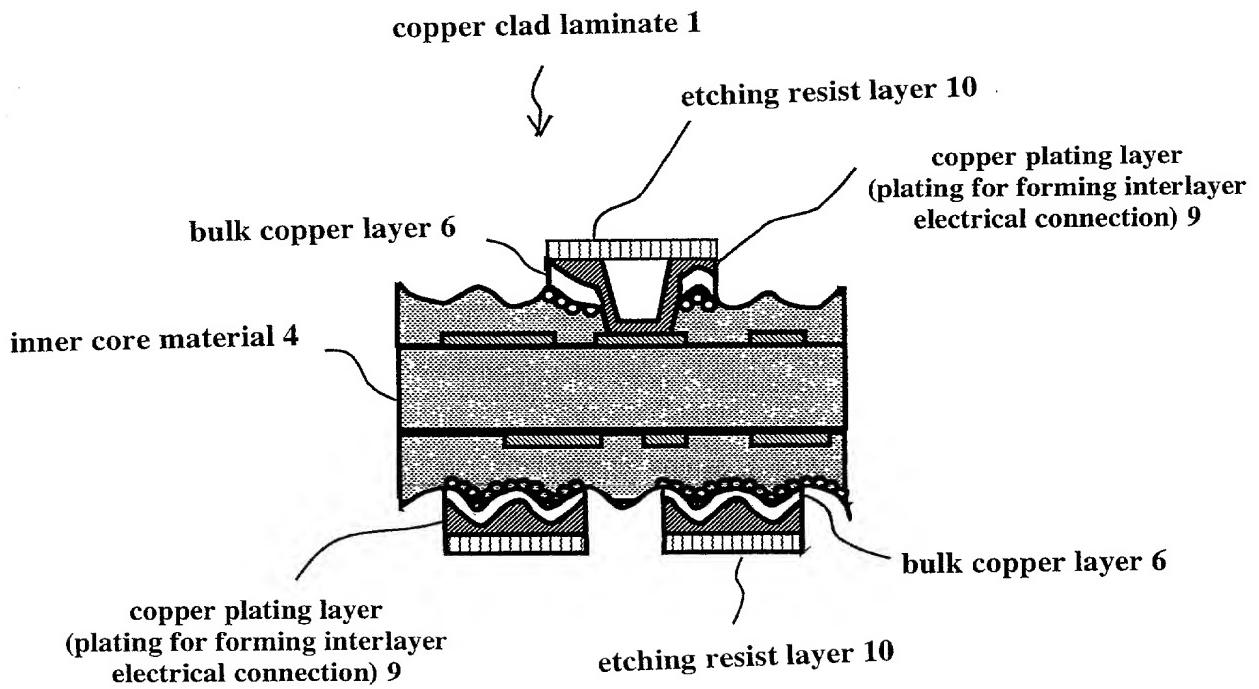


FIG. 9

(h) Peering of Etching Resist Layers

